ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier	Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
nsemi											2024-05-05				
Contact N	ame		Title - Conta	Title - Contact			Phone - Contact*				Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Da	Oate Version Manufacturing Site			Weight*	UOM	Unit Type		
		NCN8025AMNTXG SMART		SMART CARD IC	MART CARD IC		2024-05-05		1	MY1		44.91	mg	Each	
Manufa	cturing Proccess Informa	ation		,											
	Terminal Plating / Grid Array Material Termina			rminal Base Alloy J-STD-020 MSL Ra			ng Peak Process Body Temperature Max Time at Pea			Tempera	ture Nun	nber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU Alloy 1					260		C	30	secor	ds 3					
Comments															
vel 1 - m	aximum time at peak temperat	ture during sol	dering is 10-3	0 seconds											
or more	information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier pr											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.98	mg	Supplier	Silicon (Si)	7440-21-3		2.98	mg
Die Attach	0.55	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.11	mg
			Supplier	Silver (Ag)	7440-22-4		0.44	mg
Lead Frame	16.85		Supplier	Silver (Ag)	7440-22-4		0.1685	mg
			Supplier	Tin (Sn)	7440-31-5		0.0421	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0371	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0421	mg
			Supplier	Copper (Cu)	7440-50-8		16.5602	mg
Mold Compound-Black	22.31		Supplier	Epoxy and Phenolic Resin	40216-08-8		1.7848	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1115	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.4462	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		19.2981	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.6693	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.33	mg	Supplier	Gold (Au)	7440-57-5		0.33	mg